

Features:

1. Optimized design and advanced technology, excellent and precise manufacturing;
2. Advanced technology application and creation to reassure the best machine performance;
3. Adhering to the rigorous and pragmatic tradition of equipment manufacturing, the machine is durable w
4. The most efficient heating and conduction, allows ΔT control inside the chamber to be $\pm 1^\circ\text{C}$
5. The exclusive patented flux collection system makes the chamber clean, reduce maintenance time and cost; Intelligent nitrogen monitoring and control system and valve control, according to the oxygen content in the cha
6. High performance and durable seals are used, advanced design ensures good air tightness, the oven achieves a
7. User-friendly operation interface, advanced touch screen technology; using USB to secure installation, softwa
8. Automatic switch on/off function, convenient for operators to save time, especially for one-shift production (f
9. Wide range of applications for all SMT production soldering processes. Preheating zone can be set to a maximum of $300\text{-}350^\circ\text{C}$, vacuum zone can be set to a maximum of 300°C
10. Patented in-line vacuum system, can reduce void rate by 99%. The standard width of vacuum chamber is 510
11. The cycle time is from 45 to 90s, vacuuming can be finished in around 30s;
12. Optimized design with single-step pumping or step-by-step pumping. It can be divided into 5 steps (e.g. from
13. Minimum vacuum can reach 1 mbar, void rate is less than 1% of individual solder joints, less than 5% for the whole PCB. This is something that standard hot air reflow oven can never achieve. It is widely used in the soldering of semiconductor, bare chips in ceramics, copper PCB LED, BGA, and high-power components;